

FORM PTO-1595 RECORDATIC 1/31/92 7-3-03 PATENTS	102489511 :PARTMENT OF COMMERCE ONLY Patent and Trademark Office
To the Honorable Commissioner of Patents and Trademar thereof.	rks: Please Record the attached original documents or copy
Name of conveying party(ies):	Name and address of receiving party(ies):     Name: _Sony Corporation
SHIGETAKA TOMIYA TOMONORI HINO	Internal Address:
Additional name(s) of conveying party(ies) attached?	Shinagawa-ku, Tokyo 141, Japan
☐ Yes ☒ No	Street Address:
3. Nature of conveyance:  ☑ Assignment ☐ Merger  ☐ Security Agreement ☐ Change of Name  ☐ Other  Execution Date April 10 and 14, 2003	City:State:Zip:  Additional Name(s) & Address(es) attached □ Yes ☒ No
4. Application (number(s) or patent number(s): If this document is being filed together with a new	application, the execution date of the application is:
A. Patent Application No.(s) U.S. Serial No. 10 <u>/343,878 filed</u> February 5, Attorney Docket No. 09792909-5567	B: Patent No.(s) 2003
Additional numbers attached? 口 Yes 区 No	C11 2:
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved  1 7. Total Fee (37 CFR 3.41 \$ 40.00
SONNENSCHEIN NATH & ROSENTHAL P.O. Box #061080 Wacker Drive Station	☐ Enclosed  ☑ Authorized to be charged to American Express Acct. No. 378571697401002. Form 2038 is attached for that purpose.
Sears Tower Chicago, IL 60606-1080	Any deficiency is authorized to be charged to deposit account or any additional fees
Customer ID No. 26263	8. Deposit Account Number: 19.3140
	(Attach duplicate copy of this page if paying by deposit account)
David R. Metzger	June 30, 2003  Date  Total number of pages 3
Mail Stop Assignme P.O.	sheet information to: oner for Patents ent Recordation Services Box 1450 , VA 22313-1450
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**PATENT** 

**REEL: 014224 FRAME: 0488** 

ASSI	CN	MIT	NT

Docket Number:	

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in NITRIDE SEMICONDUCTOR LASER

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No. PCT/JP02/05509, International Filing Date: June 4, 2002

This assignment executed on the dates indicated below.

SHIGETAKA TOMIYA		
Name of first or sole inventor	Execution date of U.S. Patent Application	
TOKYO, JAPAN Residence of first or sole inventor		
Signature of tirstor sole inventor	April 10, 2003  Date of this assignment	

PATENT REEL: 014224 FRAME: 0489

TOMONORI HINO	
Name of second joint inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of second joint inventor  Signature of second joint inventor	April 14 2003 Date of this assignment
Signature of second joint inventor	Date of this assignment
Name of third joint inventor	Execution date of U.S. Patent Application
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Residence of third joint inventor	
Signature of third joint inventor	Date of this assignment
Name of fourth joint inventor	Execution date of U.S. Patent Application
Residence of fourth joint inventor	
Signature of fourth joint inventor	Date of this assignment
Name of fifth joint inventor	Execution date of U.S. Patent Application
Residence of fifth joint inventor	

PATENT REEL: 014224 FRAME: 0490

Date of this assignment

RECORDED: 07/03/2003

Signature of fifth joint inventor